

**APPLICATION DATA SHEET****Inventor Information**

Inventor One Given Name	:	Sion C.
Family Name	:	Quinlan
Postal Address Line One	:	1, Lockstile Way
Postal Address Line Two	:	Goring on Thames
City	:	Oxon
Country of Residence	:	United Kingdom
Citizenship Country	:	United Kingdom
 Inventor Two Given Name	:	 Tim J.
Family Name	:	Bales
Postal Address Line One	:	15 Derbyshire Green
Postal Address Line Two	:	Warfield
City	:	Bracknell
Country of Residence	:	United Kingdom
Citizenship Country	:	United Kingdom

**Correspondence Information**

Name Line One	:	Steven H. Arterberry, Esq.
Address Line One	:	DORSEY & WHITNEY LLP
Address Line Two	:	1420 Fifth Avenue, Suite 3400
City	:	Seattle
State or Province	:	Washington
Postal or Zip Code	:	98101
Telephone	:	206-903-8800
Facsimile	:	206-903-8820
E-Mail	:	patentseattle@dorseylaw.com

**Application Information**

Title	:	SEMICONDUCTOR PACKAGE ASSEMBLY AND METHOD FOR ELECTRICALLY ISOLATING MODULES
Total Drawing Sheets	:	3
Formal Drawings	:	YES
Application Type	:	Utility
Attorney Docket Number	:	30022/US/2
Assigned	:	Yes (Large Entity)

**Representative Information**

Representative Customer No.	:	27,076
-----------------------------	---	--------

**Continuity Information**

This application is a : divisional of  
>Application One : 10/057,205  
Filing Date : January 25, 2002

**Prior Foreign Application**

Foreign Application One : 0126821.8  
Filing Date : November 7, 2001  
Country : United Kingdom  
Priority Claimed : Yes

\sefile03\files\ip\forms\patent\application data sheet.doc  
4832-7702-3744\1 7/29/2003